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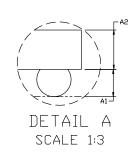


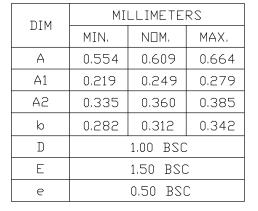
WLCSP6 1.0x1.5x0.609 CASE 567FH ISSUE A

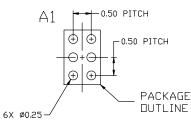
DATE 21 JUN 2022

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.





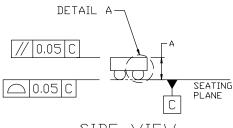


RECOMMENDED MOUNTING FOOTPRINT*

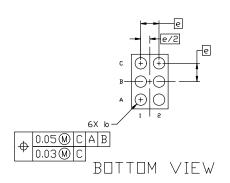
For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

PIN 1 REFERENCE 2X \(\times 0.05 \(\times \) 2X \(\times 0.05 \(\times \)









GENERIC MARKING DIAGRAM*



XXX = Specific Device CodeA = Assembly Location

Y = Year

W = Work Week

■ = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

9.			
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